

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

30.03.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	361		2	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		4	
B-RS-FR4-ML-0.711mm-018+018-TG150-HF-...	50203033	18	L2	5	
		711			
		18	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	361		6	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		7	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		8	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	9	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1505 µm

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